

**LOCATION:**

Haywards BBQ  
11051 S Antioch  
Overland Park, KS 66210  
[www.haywardsbbq.com](http://www.haywardsbbq.com)

Map and directions posted on  
[www.heartlandsmta.com](http://www.heartlandsmta.com)



**Heartland**  
**SMTA**  
Surface Mount Technology Association

**Aug 17 '11**  
**5:00 - 8:30 PM**

**Haywards BBQ****COST (includes BBQ Dinner):**

\$ \$20 SMTA Registered Members  
\$ \$10 Full Time Students  
\$ \$30 Non-Members  
(cash or check to Heartland SMTA  
or PayPal at [www.heartlandsmta.com](http://www.heartlandsmta.com))

**RSVP By Aug 12<sup>th</sup>**

**Dwight Nelson**  
dnelson@lorenzsouth.com  
(email preferred)  
(913) 469-1312

**SMT Assembly Challenges and Proven Solutions for Increasing Yields**

**By Robert Dervaes**

**V.P. Technology, FCT Assembly, Colorado Springs, CO**

Surface mount technology (SMT) assemblies are getting more complex as advancements in the areas of printed circuit board (PCB) manufacturing and component design become more mainstream. Most SMT manufacturing processes have to now be capable of building “hybrid” assemblies, which contain both previous generation technology and recent technological advancements. Maintaining, or improving, SMT process yields is getting more difficult as most assembly lines have a mixture of newer and older equipment. Many of the SMT process variables are directly controlled by the contract manufacturer. However, there are some, i.e. PCB design, PCB fab, component design, component substitution, contamination, and solder paste stencil fab, where the contract manufacturer is completely reliant upon their supplier quality. What challenges can contract manufacturers expect to face when building these advanced assemblies and what can be done to improve process yields?

Technological advancements in the areas of stencil lasers, materials, nano-coatings, and aperture registration accuracies will be presented, along with a discussion of how these new technologies can improve process yields.

**About the Speaker:**

Robert Dervaes has more than 19 years of design and manufacturing engineering experience in the electronics manufacturing industry, working for both the commercial and defense industries. He has been with FCT Assembly for over 7 years and currently directs the technical development and engineering efforts for its Fine Line Stencil and FCT Solder divisions as V.P. of Technology. He is a member of the IPC Stencil Design Task Group and has a published white paper entitled “Conquering SMT Stencil Printing Challenges with Today’s Miniature Components.” Robert holds a bachelor’s degree in Mechanical Engineering from Kansas State University.

***Door opens at 4:30 - come early and network!***

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